

General Description

The MAX3625B is a low-jitter, precision clock generator optimized for networking applications. The device integrates a crystal oscillator and a phase-locked loop (PLL) clock multiplier to generate high-frequency clock outputs for Ethernet, 10G Fibre Channel, and other networking applications.

This proprietary PLL design features ultra-low jitter and excellent power-supply noise rejection, minimizing design risk for network equipment.

The MAX3625B has three LVPECL outputs. Selectable output dividers and a selectable feedback divider allow a range of output frequencies.

Applications

Ethernet Networking Equipment Fibre Channel Storage Area Network

Typical Application Circuit appears at end of data sheet.

_____Features

- ♦ Crystal Oscillator Interface: 24.8MHz to 27MHz
- ♦ CMOS Input: Up to 320MHz
- **♦ Output Frequencies**

Ethernet: 62.5MHz, 125MHz, 156.25MHz, 312.5MHz 10G Fibre Channel: 159.375MHz, 318.75MHz

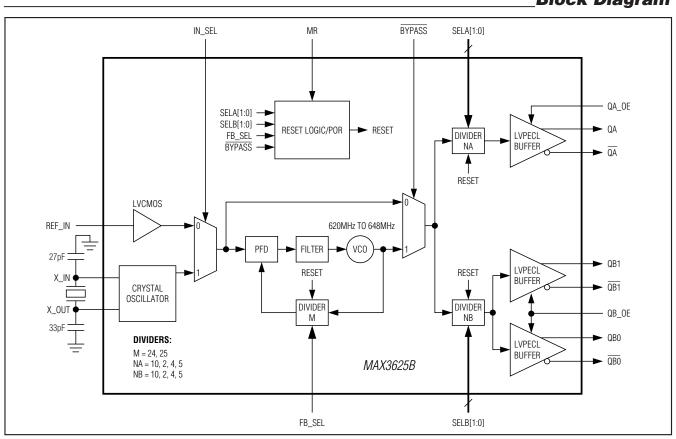
- **♦ Low Jitter**
 - 0.14ps_{RMS} (1.875MHz to 20MHz) 0.36ps_{RMS} (12kHz to 20MHz)
- **♦** Excellent Power-Supply Noise Rejection
- ♦ No External Loop Filter Capacitor Required

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX3625BEUG+	-40°C to +85°C	24 TSSOP-EP*

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

Block Diagram



^{*}EP = Exposed pad.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage Range VCC, VCCA,	Voltage Range at X_OUT0.3V to (VCC - 0.6V)
V _{CCO_A} , V _{CCO_B} 0.3V to +4.0V	Current into QA, QA, QB0, QB0, QB1, QB156mA
Voltage Range at REF_IN, IN_SEL,	Continuous Power Dissipation (T _A = +70°C)
FB_SEL, SELA[1:0], SELB[1:0],	24-Pin TSSOP (derate 26.7mW/°C above +70°C)2133.3mW
QA_OE, QB_OE, MR, BYPASS0.3V to (V _{CC} + 0.3V)	Operating Junction Temperature Range55°C to +150°C
Voltage Range at X_IN0.3V to +1.2V	Storage Temperature Range65°C to +160°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +3.0 \text{V to } +3.6 \text{V}, T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} = +3.3 \text{V}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.}$ (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Dower Cumply Current (Note 2)	loo	IN_SEL = high		72	98	mA
Power-Supply Current (Note 3)	Icc	IN_SEL = low		74] IIIA
CONTROL INPUT CHARACTER (SELA[1:0], SELB[1:0], FB_SEL		_OE, QB_OE, MR, BYPASS Pins)				
Input Capacitance	CIN			2		pF
Input Pulldown Resistor	RPULLDOWN	Pins MR, FB_SEL		75		kΩ
Input Logic Bias Resistor	R _{BIAS}	Pins SELA[1:0], SELB[1:0]		50		kΩ
Input Pullup Resistor	R _{PULLUP}	Pins QA_OE, QB_OE, IN_SEL, BYPASS		75		kΩ
LVPECL OUTPUTS (QA, $\overline{\text{QA}}$, QE	30, QB 0, QB1,	QB1 Pins)				
Output High Voltage	VoH		V _{CC} - 1.18	V _{CC} - 0.98	V _{CC} - 0.83	V
Output Low Voltage	V _{OL}		V _{CC} - 1.90	V _{CC} - 1.7	V _{CC} - 1.55	V
Peak-to-Peak Output-Voltage Swing (Single-Ended)		(Note 2)	0.6	0.72	0.9	V _{P-P}
Clock Output Rise/Fall Time		20% to 80% (Note 2)	200	350	600	ps
Output Duty Cycle Distortion		PLL enabled	48	50	52	%
Output Duty-Cycle Distortion		PLL bypassed (Note 4)	45	50	55	70
LVCMOS/LVTTL INPUTS (SELA[1:0], SELB[1:0], FB_SEL	, IN_SEL, QA	_OE, QB_OE, MR, BYPASS Pins)	•			
Input-Voltage High	VIH		2.0			V
Input-Voltage Low V _{IL}					0.8	V
Input High Current	ent I _{IH} V _{IN} = V _{CC}				80	μΑ
Input Low Current	lıL	V _{IN} = 0V	-80			μΑ

2 ______

ELECTRICAL CHARACTERISTICS (continued)

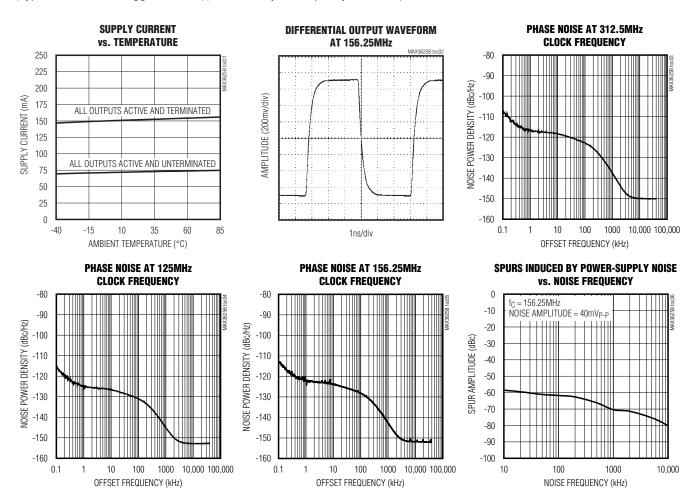
 $(V_{CC} = +3.0 \text{V to } +3.6 \text{V}, T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} = +3.3 \text{V}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.}$ (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
REF_IN SPECIFICATIONS (Input	DC- or AC-C	coupled)				•
Deference Cleak Francisco		PLL enabled	24.8		27.0	MHz
Reference Clock Frequency		PLL bypassed			320	WIHZ
Input-Voltage High	VIH		2.0			V
Input-Voltage Low	VIL				0.8	V
Input High Current	IIH	VIN = VCC			240	μΑ
Input Low Current	I _I L	V _{IN} = 0V	-240			μΑ
Reference Clock Duty Cycle		PLL enabled	30		70	%
Input Capacitance				2.5		рF
CLOCK OUTPUT AC SPECIFICA	TIONS		·			
VCO Frequency Range			620		648	MHz
Random Jitter (Note 5)	RJ _{RMS}	12kHz to 20MHz		0.36	1.0	202110
naridom sitter (Note 3)	LINKWS	1.875MHz to 20MHz		0.14		psrms
Spurs Induced by Power-Supply Noise		(Notes 6, 7, 8)		-60		dBc
Deterministic Jitter Induced by Power-Supply Noise		(Note 9)		5.6		psp-p
Nonharmonic and Subharmonic Spurs				-70		dBc
Output Skew		Between any output pair		5		ps
		f = 1kHz		-124		
		f = 10kHz		-127		
Clock Output SSB Phase Noise at 125MHz (Note 10)		f = 100kHz		-131		dBc/Hz
at 1201/1112 (110to 10)		f = 1MHz		-145]
		f > 10MHz		-153]

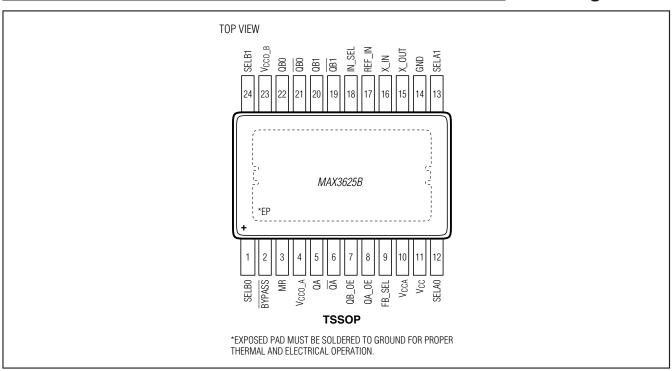
- Note 1: A series resistor of up to 10.5Ω is allowed between V_{CC} and V_{CCA} for filtering supply noise when system power-supply tolerance is $V_{CC} = 3.3V \pm 5\%$. See Figure 1.
- Note 2: LVPECL outputs guaranteed up to 320MHz.
- Note 3: All outputs enabled and unloaded.
- **Note 4:** Measured with a crystal (see Table 4) or an AC-coupled, 50% duty-cycle signal on REF_IN.
- **Note 5:** Measured with crystal source, see Table 4.
- **Note 6:** Measured using setup shown in Figure 1.
- **Note 7:** Measured with 40mV_{P-P}, 100kHz sinusoidal signal on the supply.
- **Note 8:** Measured at 156.25MHz output.
- **Note 9:** Calculated based on measured spurs induced by power-supply noise (refer to Application Note 4461: *HFAN-04.5.5: Characterizing Power-Supply Noise Rejection in PLL Clock Synthesizers*).
- Note 10: Measured with 25MHz crystal or 25MHz reference clock at REF_IN with a slew rate of 0.5V/ns or greater.

Typical Operating Characteristics

(Typical values are at $V_{CC} = +3.3V$, $T_A = +25$ °C, crystal frequency = 25MHz.)



Pin Configuration



Pin Description

PIN	NAME	FUNCTION
1, 24	SELB0, SELB1	LVCMOS/LVTTL Inputs. Control NB divider setting. Has $50 \text{k}\Omega$ input impedance. See Table 2 for more information.
2	BYPASS	LVCMOS/LVTTL Input (Active Low). Connect low to bypass the internal PLL. Connect high or leave open for normal operation. When in bypass mode the output dividers are set to divide by 1. Has internal 75k Ω pullup to VCC.
3 MR LVCMOS/LVTTL Input. Master reset input. Pulse high for > 1μs to reset all dividers. Has pulldown to GND. Not required for normal operation.		
4	V _{CCO_A}	Power Supply for QA Clock Output. Connect to +3.3V.
5 QA Noninverting Clock Output, LVPECL		Noninverting Clock Output, LVPECL
6 QA Inverting Clock Output, LVPECL		Inverting Clock Output, LVPECL
7	QB_OE	LVCMOS/LVTTL Input. Enables/disables QB clock outputs. Connect pin high or leave open to enable LVPECL clock outputs QB0 and QB1. Connect low to set QB0 and QB1 to a logic 0. Has internal $75k\Omega$ pullup to V_{CC} .
I 8 I DAOFI '		LVCMOS/LVTTL Input. Enables/disables the QA clock output. Connect high or leave open to enable the LVPECL clock output QA. Connect low to set QA to a logic 0. Has internal 75k Ω pullup to V _{CC} .
9 FB_SEL LVCMOS/LVTTL Input. Controls M divider setting. See Table 3 pulldown to GND.		LVCMOS/LVTTL Input. Controls M divider setting. See Table 3 for more information. Has internal 75k Ω pulldown to GND.

Pin Description (continued)

PIN	NAME	FUNCTION
10	VCCA	Analog Power Supply for the VCO. Connect to $+3.3V$. For additional power-supply noise filtering, this pin can connect to V_{CC} through 10.5Ω as shown in Figure 1 (requires $V_{CC} = 3.3V \pm 5\%$).
11	Vcc	Core Power Supply. Connect to +3.3V.
12, 13 SELA0, SELA1 impedance. LVCMOS/LVTTL Inputs. Control NA divider setting. See Table 2 for more information. 5		LVCMOS/LVTTL Inputs. Control NA divider setting. See Table 2 for more information. $50k\Omega$ input impedance.
14	GND	Supply Ground
15	X_OUT	Crystal Oscillator Output
16	X_IN	Crystal Oscillator Input
17	REF_IN	LVCMOS Reference Clock Input. Self-biased to allow AC- or DC-coupling.
1 18 1 IN SEL 1		LVCMOS/LVTTL Input. Connect high or leave open to use a crystal. Connect low to use REF_IN. Has internal 75k Ω pullup to VCC.
19	QB1	LVPECL, Inverting Clock Output
20	QB1	LVPECL, Noninverting Clock Output
21	QB0	LVPECL, Inverting Clock Output
22	QB0 LVPECL, Noninverting Clock Output	
23	VCCO_B	Power Supply for QB0 and QB1 Clock Output. Connect to +3.3V.
_	EP	Exposed Pad. Supply ground; connect to PCB ground for proper electrical and thermal performance.

Detailed Description

The MAX3625B is a low-jitter clock generator designed to operate at Ethernet and Fibre Channel frequencies. It consists of an on-chip crystal oscillator, PLL, programmable dividers, and LVPECL output buffers. Using a low-frequency clock (crystal or CMOS input) as a reference, the internal PLL generates a high-frequency output clock with excellent jitter performance.

Crystal Oscillator

An integrated oscillator provides the low-frequency reference clock for the PLL. This oscillator requires an external crystal connected between X_IN and X_OUT. The crystal frequency is 24.8MHz to 27MHz.

REF IN Buffer

An LVCMOS-compatible clock source can be connected to REF_IN to serve as the reference clock.

The LVCMOS REF_IN buffer is internally biased to the threshold voltage (1.4V typ) to allow AC- or DC-coupling, and is designed to operate up to 320MHz.

PLL

The PLL takes the signal from the crystal oscillator or reference clock input and synthesizes a low-jitter, high-frequency clock. The PLL contains a phase-frequency detector (PFD), a lowpass filter, and a voltage-

controlled oscillator (VCO) with a 620MHz to 648MHz operating range. The VCO is connected to the PFD input through a feedback divider. See Table 3 for divider values. The PFD compares the reference frequency to the divided-down VCO output (fvco/M) and generates a control signal that keeps the VCO locked to the reference clock. The high-frequency VCO output clock is sent to the output dividers. To minimize noise-induced jitter, the VCO supply (Vcca) is isolated from the core logic and output buffer supplies.

Output Dividers

The output dividers are programmable to allow a range of output frequencies. See Table 2 for the divider input settings. The output dividers are automatically set to divide by 1 when the MAX3625B is in bypass mode (BYPASS = 0).

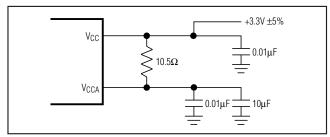


Figure 1. Analog Supply Filtering

6 _____

Table 1. Output Frequency Determination

CRYSTAL OR CMOS INPUT FREQUENCY (MHz)	FEEDBACK DIVIDER, M	VCO FREQUENCY (MHz)	OUTPUT DIVIDER, NA AND NB	OUTPUT FREQUENCY (MHz)	APPLICATIONS		
			2	312.5			
25	25	625	4	156.25	Ethernet		
25	25		625	025	5	125	Ethernet
			10	62.5			
25.78125	25	644.53125	4	161.132812	10Gbps Ethernet		
			2	312.5			
00.04100	24	005	4	156.25	Ethornot		
20.04100	24	26.04166 24 625	625	5	125	Ethernet	
			10	62.5			
26.5625	24	637.5	2	318.75	10G Fibre Channel		
20.3625			4	159.375			

LVPECL Drivers

The high-frequency outputs—QA, QB0, and QB1—are differential PECL buffers designed to drive transmission lines terminated with 50Ω to V_{CC} - 2.0V. The maximum operating frequency is specified up to 320MHz. The outputs can be disabled, if not used. The outputs go to a logic 0 when disabled.

Reset Logic/POR

During power-on, a power-on reset (POR) signal is generated to synchronize all dividers. An external master reset (MR) signal is not required.

_Applications Information Power-Supply Filtering

The MAX3625B is a mixed analog/digital IC. The PLL contains analog circuitry susceptible to random noise. In addition to excellent on-chip power-supply noise rejection, the MAX3625B provides a separate power-supply pin, VCCA, for the VCO circuitry. Figure 1 illustrates the recommended power-supply filter network for VCCA. The purpose of this design technique is to ensure a clean power supply to the VCO circuitry and to improve the overall immunity to power-supply noise. This network requires that the power supply is +3.3V ±5%. Decoupling capacitors should be used on all supply pins for best performance.

Output Divider Configuration

Table 2 shows the input settings required to set the output dividers. Note that when the MAX3625B is in bypass mode (BYPASS set low), the output dividers are automatically set to divide by 1.

PLL Divider Configuration

Table 3 shows the input settings required to set the PLL feedback divider.

Table 2. Output Divider Configuration

INP	INPUT			
SELA1/SELB1	SELA0/SELB0	NA/NB DIVIDER		
0	0	÷10		
0	1	÷2		
1	0	÷4		
1	1	÷5		

Table 3. PLL Divider Configuration

FB_SEL INPUT	M DIVIDER
0	÷25
1	÷24

Crystal Selection

The crystal oscillator is designed to drive a fundamental mode, AT-cut crystal resonator. See Table 4 for recommended crystal specifications. See Figure 3 for external capacitance connection.

Table 4. Crystal Selection Parameters

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS
Crystal Oscillation Frequency	fosc	24.8		27	MHz
Shunt Capacitance	Co		2.0	7.0	pF
Load Capacitance	CL		18		рF
Equivalent Series Resistance (ESR)	R _S			50	Ω
Maximum Crystal Drive Level				300	μW

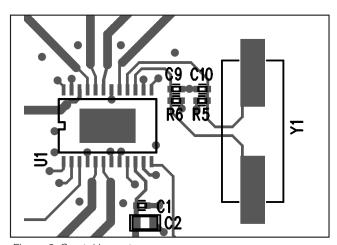


Figure 2. Crystal Layout

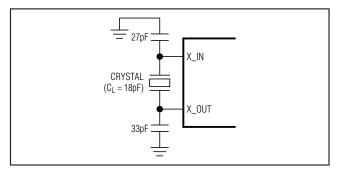


Figure 3. Crystal, Capacitors Connection

Crystal Input Layout

The crystal, trace, and two external capacitors should be placed on the board as close as possible to the MAX3625B's X_IN and X_OUT pins to reduce crosstalk of active signals into the oscillator. The example layout shown in Figure 2 gives approximately 3pF of trace plus footprint capacitance per side of the crystal. The dielectric material is FR4 and dielectric thickness of the reference board is 15 mils. Using a 25MHz crystal and the capacitor values of C10 = 27pF and C9 = 33pF, the measured output frequency accuracy is -14ppm at +25°C ambient temperature.

Interfacing with LVPECL Outputs

The equivalent LVPECL output circuit is given in Figure 7. These outputs are designed to drive a pair of 50Ω transmission lines terminated with 50Ω to VTT = VCC - 2V. If a separate termination voltage (VTT) is not available, other termination methods can be used such as shown in Figures 4 and 5. Unused outputs should be disabled and may be left open. For more information on LVPECL terminations and how to interface with other logic families, refer to Application Note 291: HFAN-01.0: Introduction to LVDS, PECL, and CML.

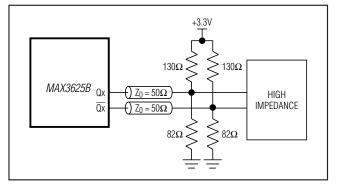


Figure 4. Thevenin Equivalent of Standard PECL Termination

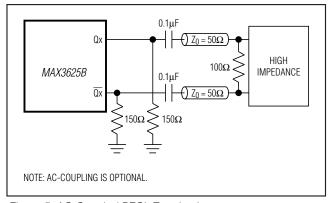


Figure 5. AC-Coupled PECL Termination

Interface Models

Figures 6 and 7 show examples of interface models.

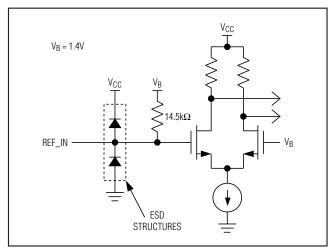


Figure 6. Simplified REF_IN Pin Circuit Schematic

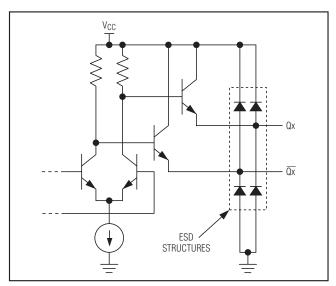


Figure 7. Simplified LVPECL Output Circuit Schematic

Layout Considerations

The inputs and outputs are critical paths for the MAX3625B, and care should be taken to minimize discontinuities on these transmission lines. Here are some suggestions for maximizing the MAX3625B's performance:

- An uninterrupted ground plane should be positioned beneath the clock I/Os.
- Supply and ground pin vias should be placed close to the IC and the input/output interfaces to allow a return current path to the MAX3625B and the receive devices.
- Supply decoupling capacitors should be placed close to the MAX3625B supply pins.
- Maintain 100 Ω differential (or 50 Ω single-ended) transmission line impedance out of the MAX3625B.
- Use good high-frequency layout techniques and multilayer boards with an uninterrupted ground plane to minimize EMI and crosstalk.
- The 24-pin TSSOP-EP package features an exposed pad (EP), which provides a low-resistance thermal path for heat removal from the IC, and must be connected to the circuit board ground plane for proper operation.

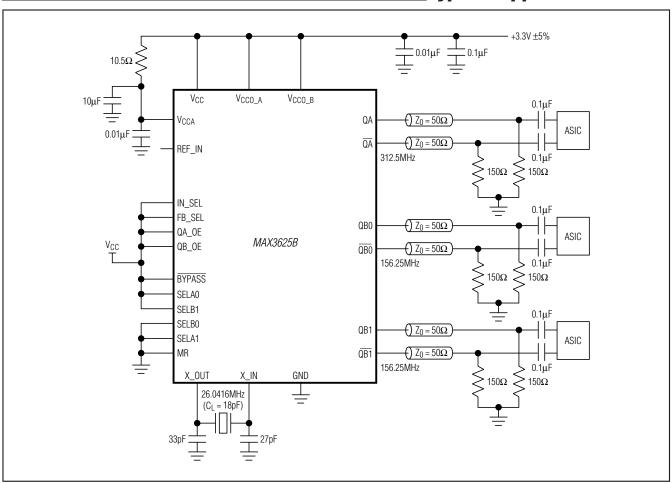
Refer to the MAX3625B Evaluation Kit for more information.

Chip Information

TRANSISTOR COUNT: 10,840

PROCESS: BICMOS

Typical Application Circuit



Package Information

For the latest package outline information and land patterns, go to www.microsemi.com. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
24 TSSOP-EP	U24E+1	<u>21-0108</u>



Microsemi Corporate Headquarters One Enterprise, Aliso Viejo CA 92656 USA Within the USA: +1 (949) 380-6100 Sales: +1 (949) 380-6136 Fax: +1 (949) 215-4996 Microsemi Corporation (NASDAQ: MSCC) offers a comprehensive portfolio of semiconductor solutions for: aerospace, defense and security; enterprise and communications; and industrial and alternative energy markets. Products include high-performance, high-reliability analog and RF devices, mixed signal and RF integrated circuits, customizable SoCs, FPGAs, and complete subsystems. Microsemi is headquartered in Aliso Viejo, Calif. Learn more at www.microsemi.com.

© 2012 Microsemi Corporation. All rights reserved. Microsemi and the Microsemi logo are trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Microsemi:

MAX3625BEVKIT+